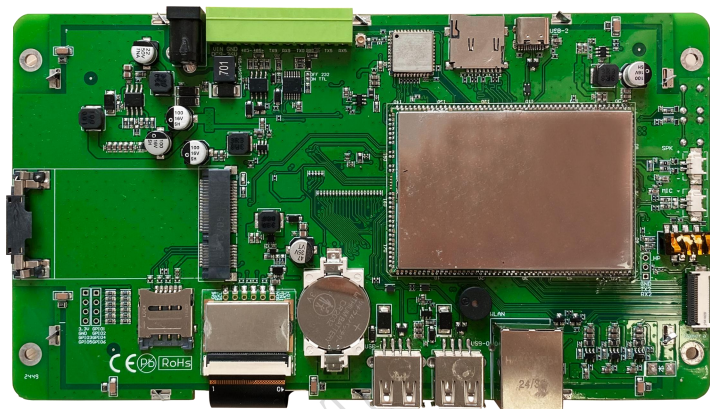
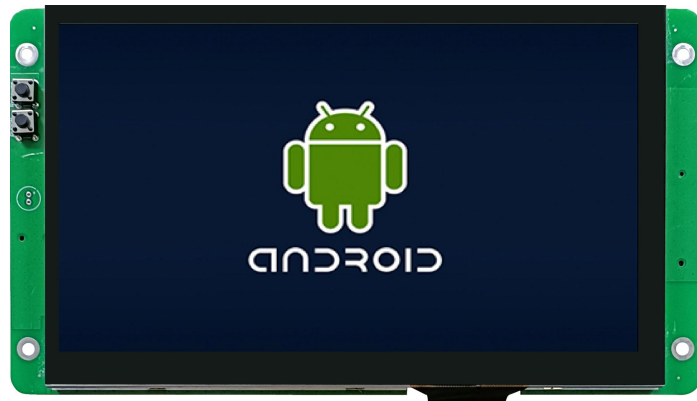


DMG10600T070_32WTC



System Hardware

Properties	Parameters
Motherboard level	Industrial-grade
CPU	RK3566, Quad-core ARM Cortex-A55, 1.8GHz Processor
OS	Android 11
Storage	8Gbytes eMMC
RAM	2Gbytes LPDDR4

Display Parameters

Properties	Parameters	Description
Size	7.0 inch	-
LCD Type	IPS, TFT LCD	-
Viewing Angle	85° /85° /85° /85°	Wide viewing angle, high contrast, and good color reproduction
Active Area (AA)	154.08mm(W)×85.92mm (H)	-
Resolution	1024×600	-
Backlight Service Life	>20000 Hrs	Backlight service life refers to the period the LED backlight operates under test conditions until brightness decreases to 50% of the initial level
Brightness	250nit	100-level brightness adjustment (Flickering may occur at 1%-30% of max brightness; not recommended for use in this range)

Note: Use dynamic screen saver to prevent afterimages from prolonged fixed page display.

Touch Parameter

Properties	Parameters
Touch Type	Capacitive touch panel
Structure	G+G structure with tempered glass surface

Power Supply

Properties	Min	Typ	Max	Unit
Power Voltage	9.0	12.0	36.0	V

Recommended power supply:12V 1A DC.

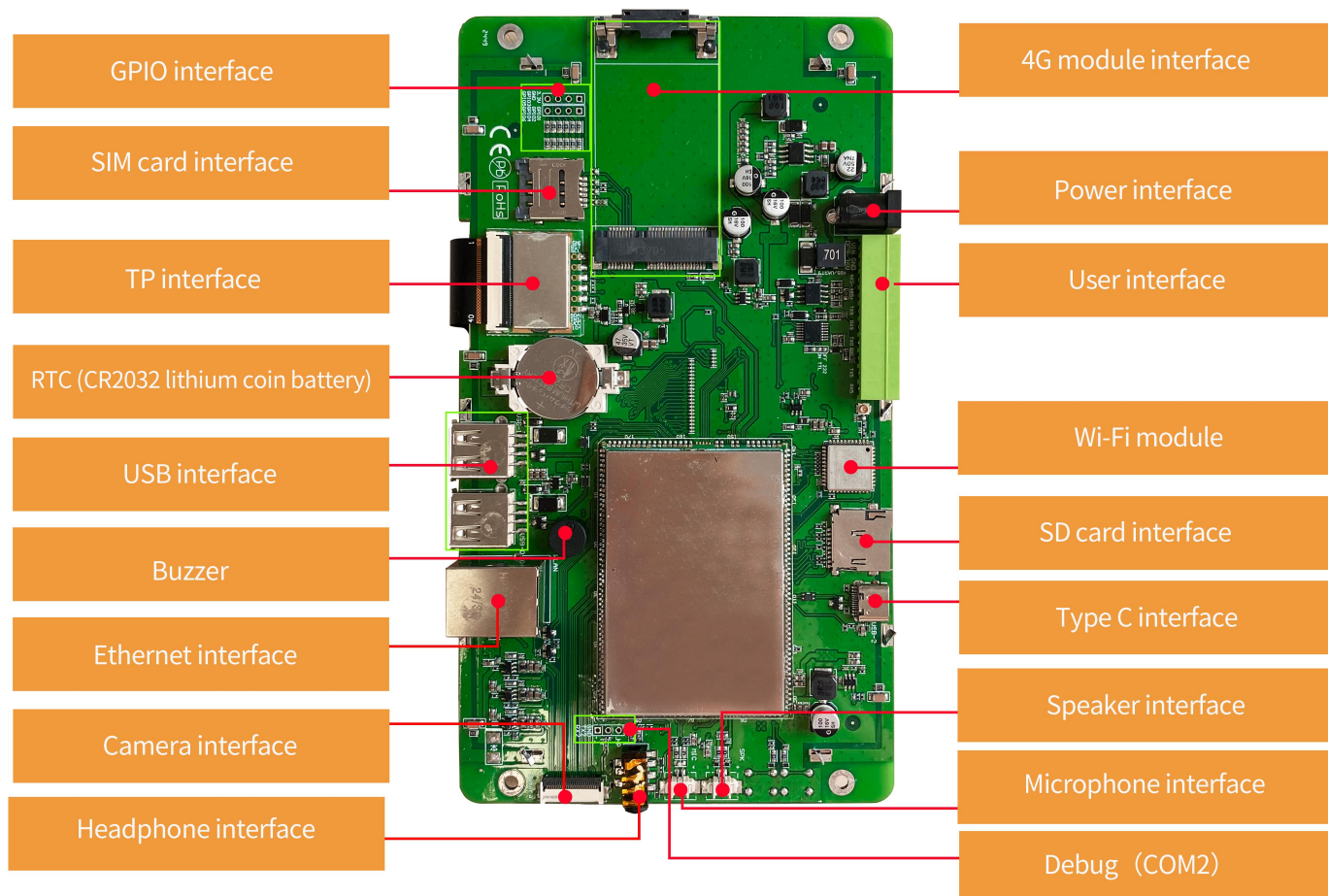
Reliability Test

Properties	Conditions	Min	Typ	Max	Unit
Working Temperature	60%RH at 12V voltage	-10	25	65	℃
Storage Temperature	-	-30	25	80	℃
Working Humidity	25℃	10%	60%	90%	RH
Conformal Coating	Y				
ESD	Air: ±8KV, Contact: ±6KV				
RE	Class B				
CE Certification	Y				

Additional cooling required for operation above 65℃.

● Peripherals and Interfaces

Properties	Description
User Interface	10Pin_3.81mm horizontal socket, power interface (3PIN_Φ2.0DH)
COM	RS232*2 (COM5 & COM9), RS485*1(COM7), RS232/TTL*1 (COM0, RS232 default), TTL*1(COM2, debug)
USB	USB 2.0*2 (HOST), Type C*1 (OTG)
Headphone	3.5mm spacing interface *1
Speaker	2Pin_1.25mm interface *1
Microphone	2Pin_1.25mm interface *1
4G module	Factory not configured, customizable to add
Camera	MIPI (24Pin_0.5mm interface)
SD card	Max. 64G
LAN	10/100Mbps
Wi-Fi	IEEE 802.11Bb/g/n, 2.4GHz, Wi-Fi 4
Bluetooth	BT4.2
RTC	Accuracy: ±20ppm @25℃
GPIO Interface	GPIO*6

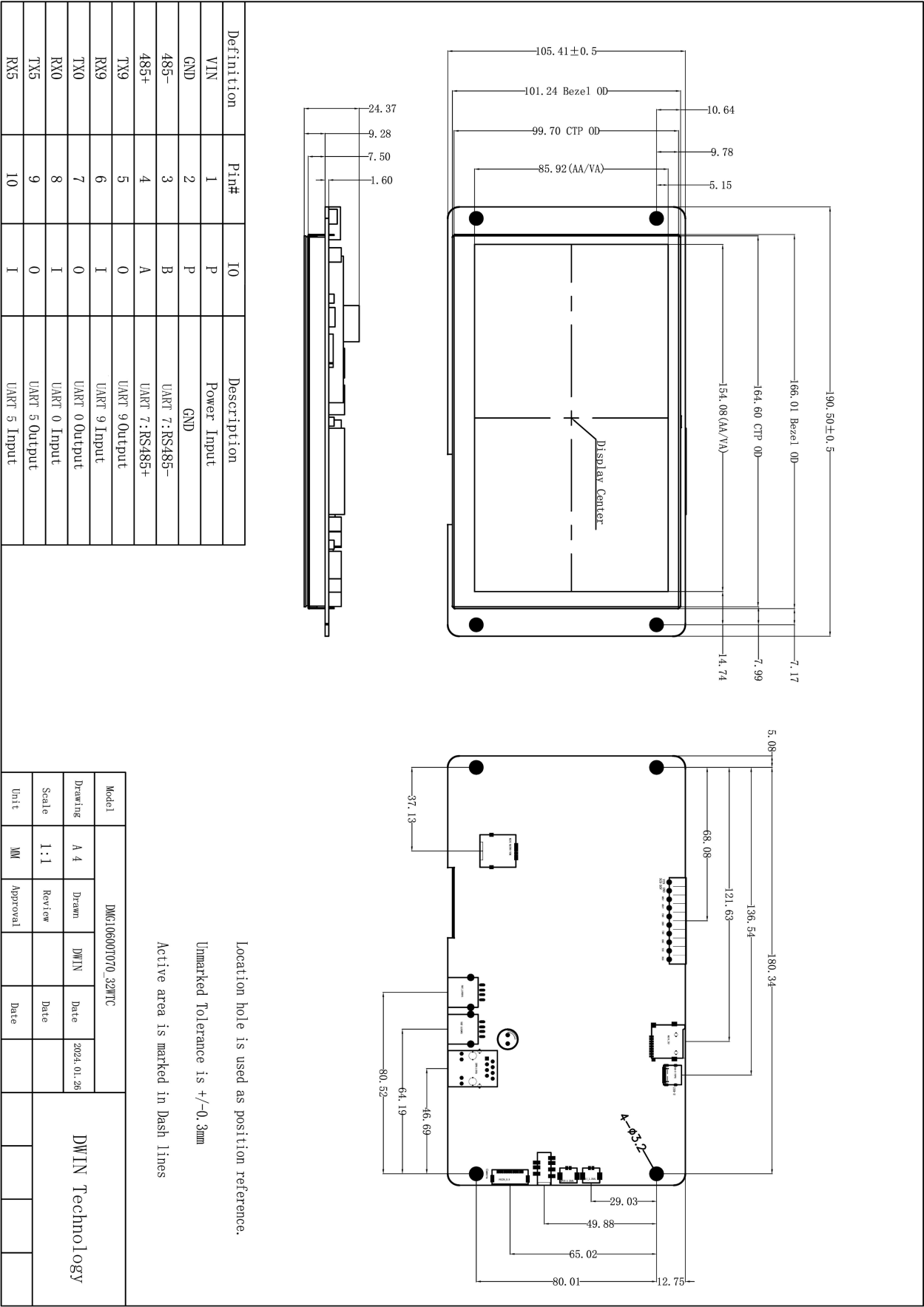


● Development Platform

Development	
Android	Java, Kotlin, C++

● Packing Capacity & Dimension

Dimension				
Dimension	190.50(W)×105.41(H)×24.37(T)mm			
Net Weight	340g			
Packing Capacity				
Model	Size	Layer	Quantity/Layer	Quantity (Pcs)
Carton1:	220mm(L)×160mm(W)×47mm	-	-	-
Carton2:	250mm(L)×200mm(W)×80mm	2	1	2
Carton3:	320mm(L)×270mm(W)×80mm	2	2	4
Carton4:	450mm(L)×350mm(W)×300mm	1	10	10
Carton5:	600mm(L)×450mm(W)×300mm	1	20	20



Revision Records

Rev.	Revise Date	Content	Editor
00	2025-02-17	First Edition	Chen
01	2025-03-12	Add the description of Bluetooth	Chen
02	2025-06-16	Update the appearance and rang of temperature & Update the description of Wi-Fi module	Chen

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Thank you all for continuous support of DWIN, and your approval is the driving force of our progress!

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